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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of  
Howard et al.

Docket Number: TI-36332

Serial No.: 10/659,181

Art Unit: 2815

Filed: 09/10/2003

Examiner: S. Clark

For: METHOD AND SYSTEM FOR PACKAGING BALL GRID ARRAYS

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NAME OF INVENTOR(S): <b>HOWARD ET AL.</b>		RECEIPT DATE & SERIAL NO.: Serial No.: <b>10/659,181</b> Conf. No: <b>7485</b>	
TITLE OF INVENTION: <b>METHOD AND SYSTEM FOR ...</b>			
TI FILE NO.: <b>TI-36332</b>	DEPOSIT ACCT. NO.: <b>20-0668</b>		
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